

104895-5 ✓ ACTIVE

AMPMODU | AMPMODU 50/50 Grid

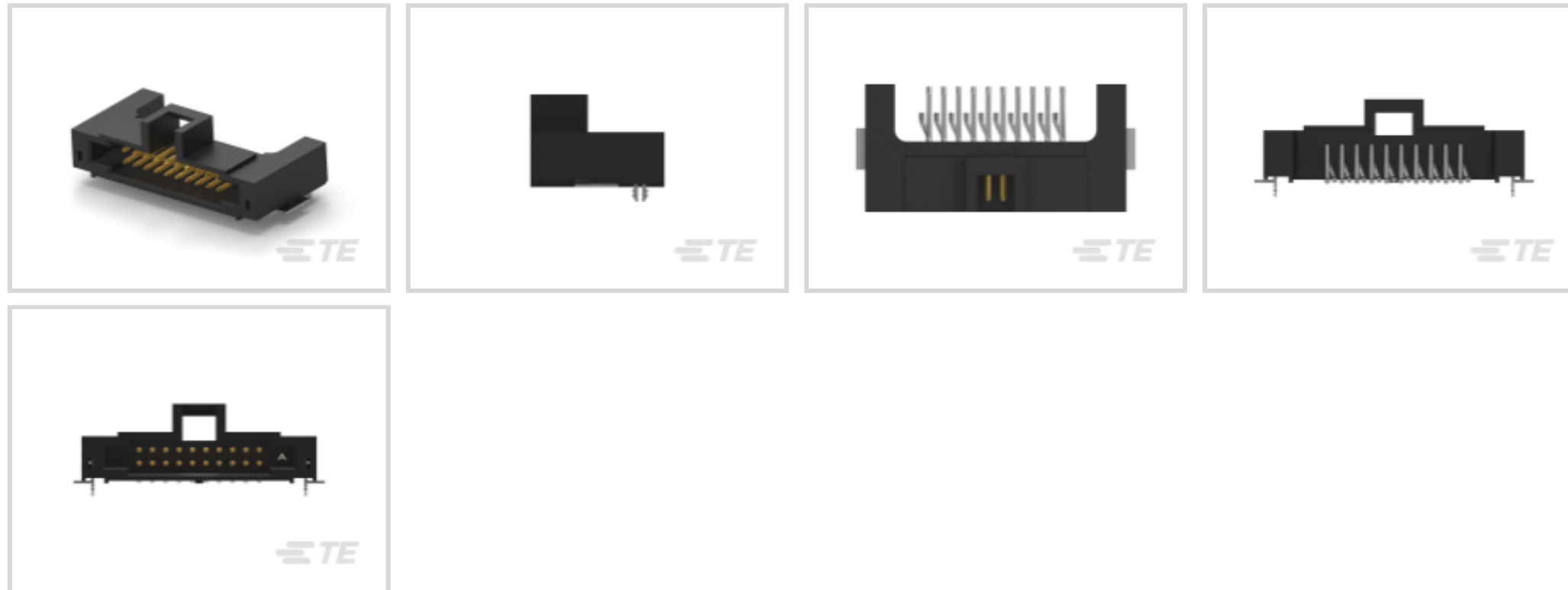
TE Internal #: 104895-5

PCB Mount Header, Right Angle, Board-to-Board, 50 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Surface Mount, AMPMODU 50/50 Grid

[View on TE.com >](#)



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Board-to-Board**

Number of Positions: **50**

Number of Rows: **2**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Fully Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Right Angle |
| Number of Positions | 50 |
| Number of Rows | 2 |

Electrical Characteristics

| | |
|-------------------|--------|
| Operating Voltage | 30 VAC |
|-------------------|--------|

Body Features

| | |
|-------------------|----------|
| Connector Profile | Standard |
|-------------------|----------|



| | |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|

Contact Features

| | |
|--|---------|
| | 150 µin |
|--|---------|

| | |
|--|-------|
| PCB Contact Termination Area Plating Material Finish | Matte |
|--|-------|

| | |
|----------------------|--------|
| Contact Shape & Form | Square |
|----------------------|--------|

| | |
|---|--------|
| Contact Mating Area Plating Material Finish | Bright |
|---|--------|

| | |
|-------------------------------|--------|
| Contact Underplating Material | Nickel |
|-------------------------------|--------|

| | |
|---|----------|
| PCB Contact Termination Area Plating Material | Tin-Lead |
|---|----------|

| | |
|-----------------------|-------|
| Contact Base Material | Brass |
|-----------------------|-------|

| | |
|--------------------------------------|------|
| Contact Mating Area Plating Material | Gold |
|--------------------------------------|------|

| | |
|--------------|-----|
| Contact Type | Pin |
|--------------|-----|

| | |
|------------------------------|------|
| Contact Current Rating (Max) | .5 A |
|------------------------------|------|

Termination Features

| | |
|---|---------------|
| Termination Method to Printed Circuit Board | Surface Mount |
|---|---------------|

Mechanical Attachment

| | |
|------------------|------|
| Mating Retention | With |
|------------------|------|

| | |
|---------------------|---------|
| Panel Mount Feature | Without |
|---------------------|---------|

| | |
|--------------------------|----------------|
| PCB Mount Retention Type | Hold-Down Post |
|--------------------------|----------------|

| | |
|------------------|------|
| Mating Alignment | With |
|------------------|------|

| | |
|-----------------------|---------|
| Mating Alignment Type | Latched |
|-----------------------|---------|

| | |
|---------------------|------|
| PCB Mount Retention | With |
|---------------------|------|

| | |
|---------------------|------|
| PCB Mount Alignment | With |
|---------------------|------|

| | |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

| | |
|--------------------|------------------|
| Centerline (Pitch) | 1.27 mm [.05 in] |
|--------------------|------------------|

| | |
|------------------|------------------------------|
| Housing Material | LCP (Liquid Crystal Polymer) |
|------------------|------------------------------|

Dimensions

| | |
|--------------------|------------------|
| Row-to-Row Spacing | 1.27 mm [.05 in] |
|--------------------|------------------|

Usage Conditions

| | |
|-----------------------------|-----------------------------|
| Operating Temperature Range | -65 – 105 °C [-85 – 221 °F] |
|-----------------------------|-----------------------------|

Operation/Application

| | |
|------------------------|----------------|
| Solder Process Feature | Board Standoff |
|------------------------|----------------|



Circuit Application

Power & Signal

Industry Standards

Approved Standards

CSA LR7189, UL E28476

UL Flammability Rating

UL 94V-0

Packaging Features

Packaging Quantity

12

Packaging Type

Box, Tube

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU

Not Compliant

EU ELV Directive 2000/53/EC

Compliant with Exemptions

China RoHS 2 Directive MIIT Order No 32, 2016

Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUNE 2022 (224)
Candidate List Declared Against: JUNE 2022 (224)
SVHC > Threshold:
Pb (40% in Component Part)
Article Safe Usage Statements:
Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 260°C

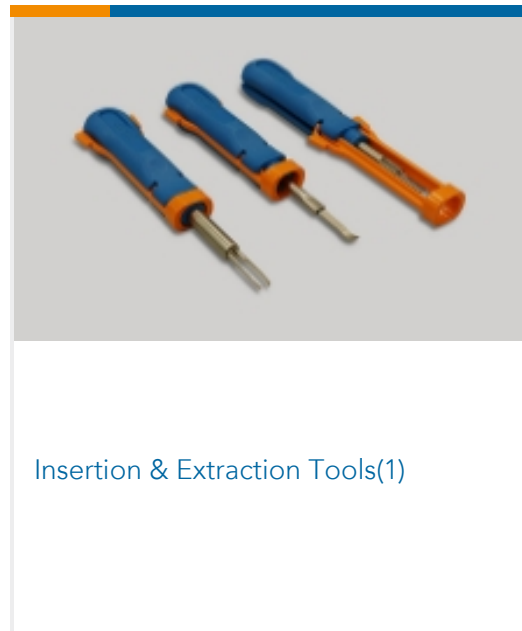
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | AMPMODU 50/50 Grid



Documents

CAD Files

3D PDF

English

Customer View Model

[ENG_CVM_104895-5_H.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_104895-5_H.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_104895-5_H.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English

Agency Approvals

UL Report

English